



Smart Machines and Intelligent Manufacturing

Guest Editors:

Prof. Dr. Shih-Ming Wang

Department of Mechanical Engineering, National Chung Hsing University, Taichung 40227, Taiwan

Dr. Chunhui Chung

Department of Mechanical Engineering, National Cheng Kung University, Tainan City 70101, Taiwan

Prof. Dr. Ping Guo

Department of Mechanical Engineering, Northwestern University, Evanston, IL 60208-3109, USA

Deadline for manuscript submissions:

closed (10 May 2023)

Message from the Guest Editors

As the concept of Industry 4.0 has become widely implemented in the manufacturing industry with modern technologies such as AIoT, sensing technology, information technology, artificial etc., it has led to significant changes and possibilities in the methods, tools, and systems supporting the machines and factories of the future. This Special Issue on Smart Machines and Intelligent Manufacturing (SMIM) provides a platform for the review and discussion of theoretical advances, research results, and industrial experiences among scientists, researchers, industry experts, and users dealing with the issues of Smart Machines and Smart Manufacturing.

This Special Issue welcome articles with original ideas and high-quality research outcomes on smart machine development and performance enhancement for manufacturing processes such as machining, forming, additive manufacturing, auto assembly, digital manufacturing, and quality measurement, with a view to practical implementation, including industrial case studies and original solutions. Original research contributions and reviews are invited for this Special Issue.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, Embase, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](https://twitter.com/Applsci)